

REMARKS

Claims 8 and 10 -16 are pending in the present application, of which claims 10 -15 have been withdrawn from consideration. By this amendment, claim 8 has been amended, claim 16 has been cancelled and new claim 17 has been added. Applicant respectfully submits that no new matter has been added. Applicant believes that this Amendment is fully responsive to the Office Action dated December 4, 2002.

Rejections Under 35 U.S.C. §102(e)

Claims 8 and 16 stand rejected under 35 U.S.C. 102(e) as being anticipated by Tsunoi (USP 6,429,516).

This rejection is respectfully traversed.

The Examiner has specifically indicated that an interposer of the present invention is disclosed in Tsunoi as the interposer 21 with plated portion 25a as shown in Fig. 1. The plated portion 25a of the interposer 21 is in contact with the pad 24 of the circuit board 22 in order that the bump 23 is electrically contacted to the pad 24 via the plated portion 25a.

On the other hand, the interposer of the present invention, particularly a coating attached to the interposer, is spaced from the solder bump (See Fig. 18 of the present application). If the coating is contacted with the solder bump when an electronic component is mounted on the printed circuit board, a melting solder bump is collected to the coating. This may cause the insufficient conductive connection between the electronic component and the printed circuit board. The coating should be spaced from the

solder bump. Claim 8, as amended, clearly defines the aforementioned feature. Thus, it is respectfully submitted that the interposer of amended claim 8 is distinguished from the interposer 21 disclosed in Tsunoi. Accordingly, the invention specified in amended claim 8 should now be allowed into a patent.

Further, new Claim 17 emphasizes that a thickness of the interposer is sufficiently smaller than a space between the electronic component and the printed circuit board. When the thickness of the interposer becomes thinner sufficiently as compared with the space, the melting solder bump can reliably be prevented from contacting with the coating. In order to wipe out the solder bump, the coating does not have to wholly surround the solder bump. Thus, the features of claim 17 further reinforce the feature specified in amended claim 8.

In view of the aforementioned amendments and accompanying remarks, claims, as amended, are in condition for allowance, which action, at an early date, is requested.

If, for any reason, it is felt that this application is not now in condition for allowance, the Examiner is requested to contact Applicant's undersigned attorney at the telephone number indicated below to arrange for an interview to expedite the disposition of this case.

In the event that this paper is not timely filed, Applicant respectfully petitions for an appropriate extension of time. Please charge any fees for such an extension of time and any other fees which may be due with respect to this paper, to Deposit Account No. 01-2340.

RESPONSE UNDER 37 CFR §1.116

U.S. Patent Application Serial No. 09/536,993

Respectfully submitted,

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